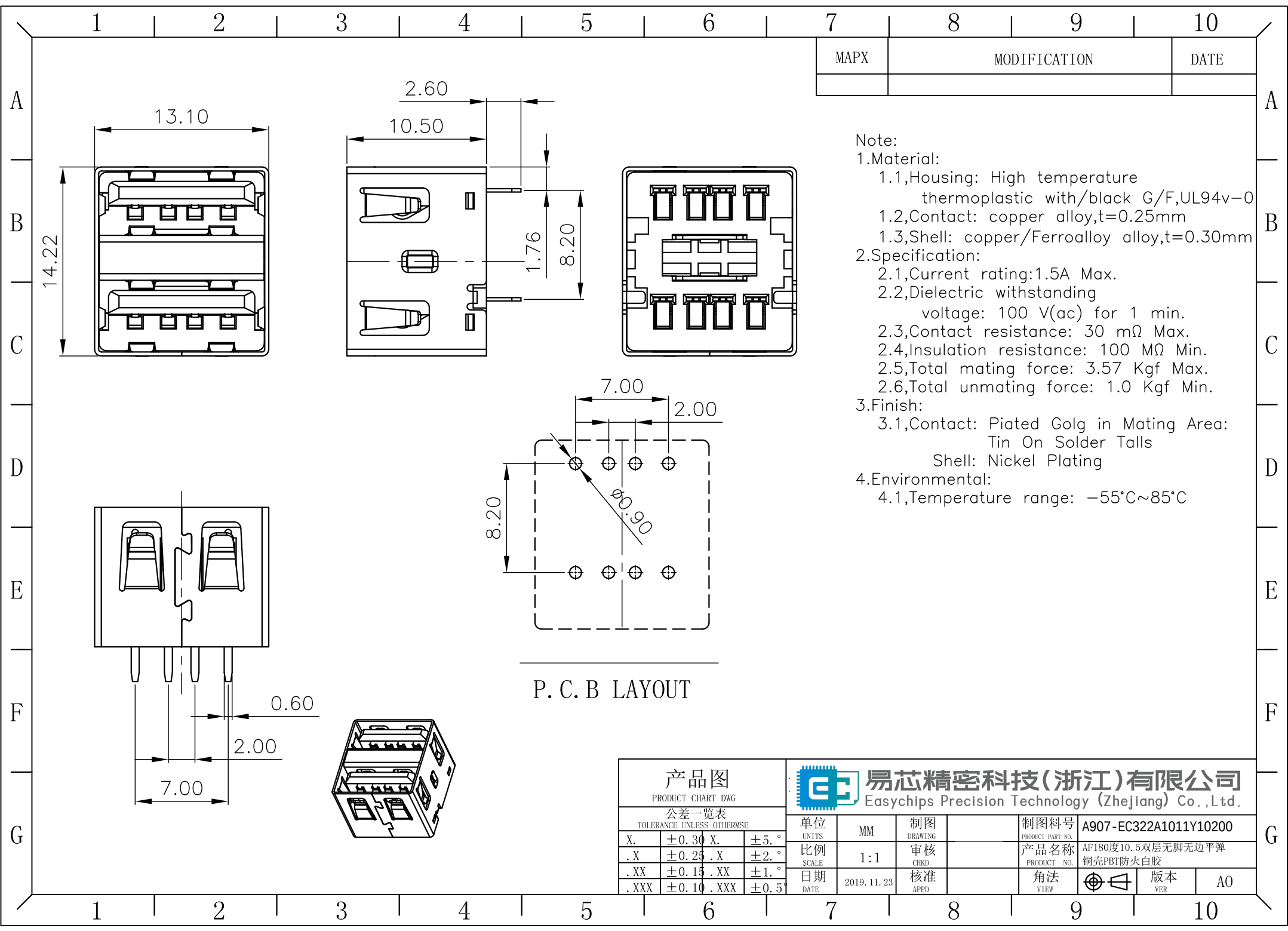




7	8	9	10
MAPX	MODIFICATION		DATE

Note:

1.Material:

1.1,Housing: High temperature thermoplastic with/black G/F,UL94v-0

1.2,Contact: copper alloy,t=0.25mm

1.3,Shell: copper/Ferroalloy alloy,t=0.30mm

2.Specification:

2.1,Current rating:1.5A Max.

2.2,Dielectric withstanding voltage: 100 V(ac) for 1 min.

2.3,Contact resistance: 30 mΩ Max.

2.4,Insulation resistance: 100 MΩ Min.

2.5,Total mating force: 3.57 Kgf Max.

2.6,Total unmating force: 1.0 Kgf Min.

3.Finish:

3.1,Contact: Plated Golg in Mating Area:
Tin On Solder Talls
Shell: Nickel Plating

4.Environmental:

4.1,Temperature range: -55°C~85°C

P. C. B LAYOUT

产品图 PRODUCT CHART DWG				易芯精密科技(浙江)有限公司 Easychips Precision Technology (Zhejiang) Co.,Ltd.			
公差一览表 TOLERANCE UNLESS OTHERWISE				单位 UNITS	MM	制图 DRAWING	制图料号 PRODUCT PART NO.
X.	±0.30	X.	±5.°	比例 SCALE	1:1	审核 CHKD	产品名称 PRODUCT NO.
.X	±0.25	.X	±2.°	日期 DATE	2019. 11. 23	核准 APPD	角法 VIEW
.XX	±0.15	.XX	±1.°				版本 VER
.XXX	±0.10	.XXX	±0.5°				AO